



## Description

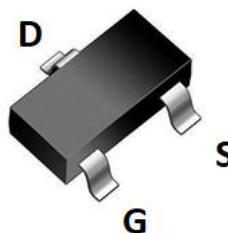
### JMT N-channel Enhancement Mode Power MOSFET

#### Features

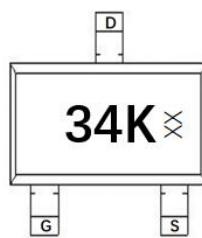
- 20V, 0.75A
- $R_{DS(ON)} < 190\text{m}\Omega$  @  $V_{GS} = 4.5\text{V}$
- $R_{DS(ON)} < 315\text{m}\Omega$  @  $V_{GS} = 2.5\text{V}$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired
- ESD Protected: 2KV

#### Application

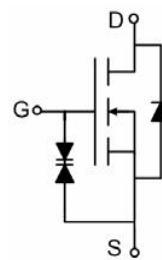
- Load Switch
- PWM Application
- Power management



SOT-523-3L top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
34K	JMTL3134KT5	TAPING	SOT-523-3L	7inch	3000	120000

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		20	V
$V_{GSS}$	Gate-Source Voltage		$\pm 10$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ\text{C}$	0.75	A
		$T_A = 100^\circ\text{C}$	0.5	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		3	A
$P_D$	Power Dissipation	$T_A = 25^\circ\text{C}$	0.17	W
$R_{\theta JA}$	Thermal Resistance, Junction to Case		735	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

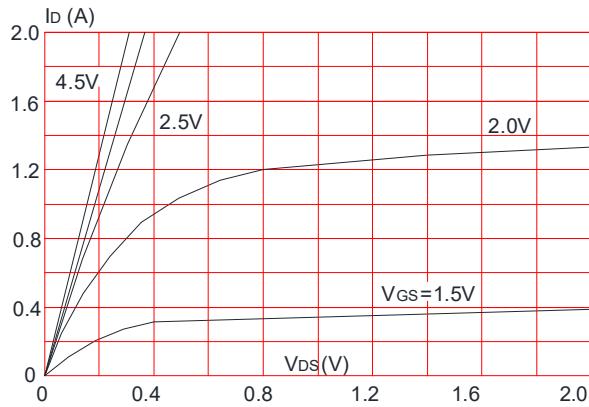
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	20	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=0\text{V}$ ,	-	-	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}= \pm 10\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	0.4	0.7	1.0	V
$R_{\text{DS}(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{\text{GS}}=4.5\text{V}$ , $I_D=0.5\text{A}$	-	145	190	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$ , $I_D=0.4\text{A}$	-	225	315	
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	-	60	-	pF
$C_{\text{oss}}$	Output Capacitance		-	22	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	12	-	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=10\text{V}$ , $I_D=0.75\text{A}$ , $V_{\text{GS}}=4.5\text{V}$	-	1	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	0.28	-	nC
$Q_{\text{gd}}$	Gate-Drain("Miller") Charge		-	0.22	-	nC
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=10\text{V}$ , $I_D=0.5\text{A}$ , $R_{\text{GEN}}=10\Omega$ , $V_{\text{GS}}=4.5\text{V}$	-	2	-	ns
$t_r$	Turn-on Rise Time		-	19	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	10	-	ns
$t_f$	Turn-off Fall Time		-	23	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	0.75	A	
$I_{\text{SM}}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	3	A	
$V_{\text{SD}}$	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=0.75\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

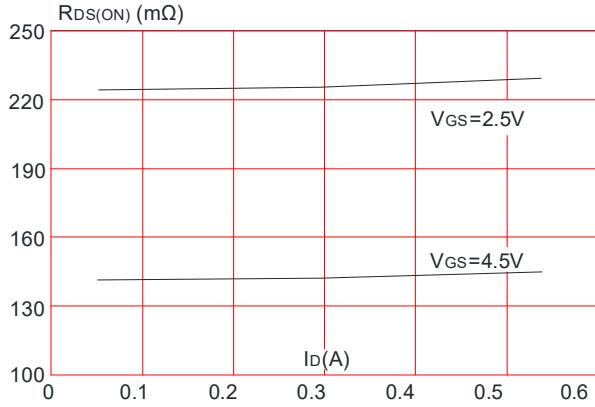
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

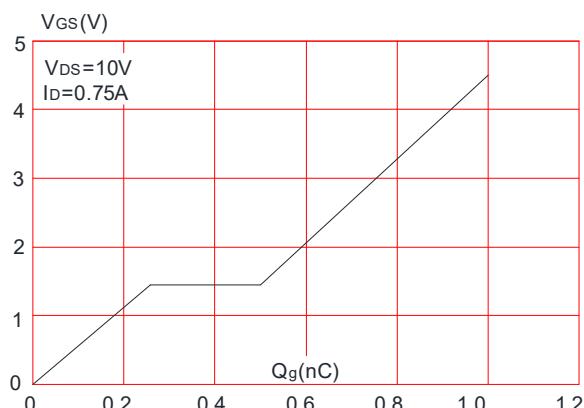
**Figure 1:** Output Characteristics



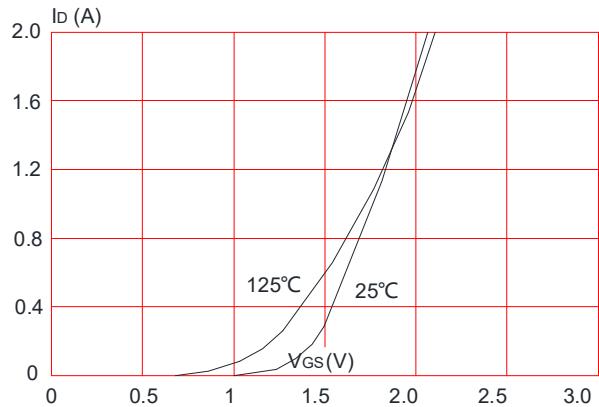
**Figure 3:** On-resistance vs. Drain Current



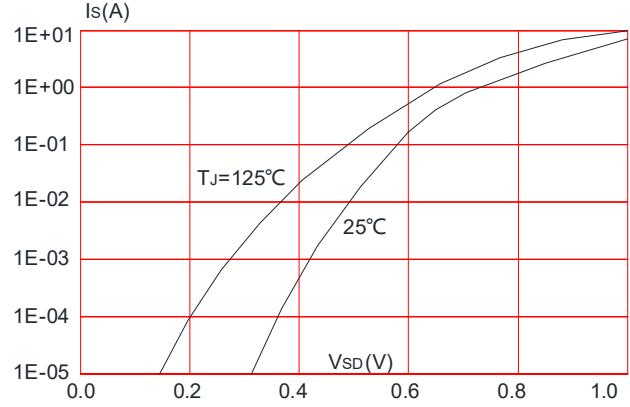
**Figure 5: Gate Charge Characteristics**



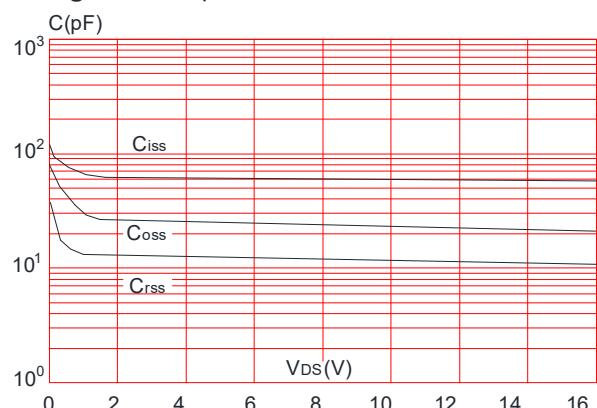
**Figure 2:** Typical Transfer Characteristics



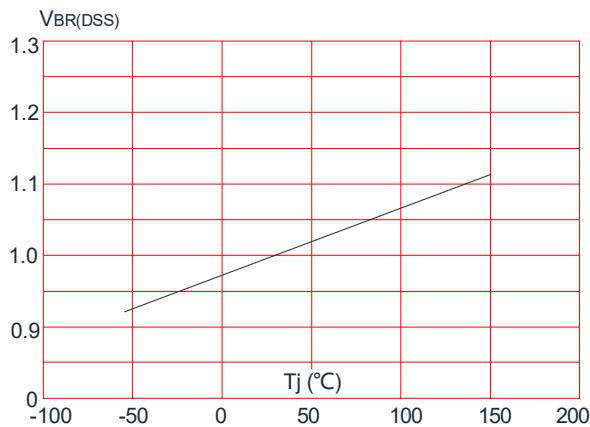
**Figure 4:** Body Diode Characteristics



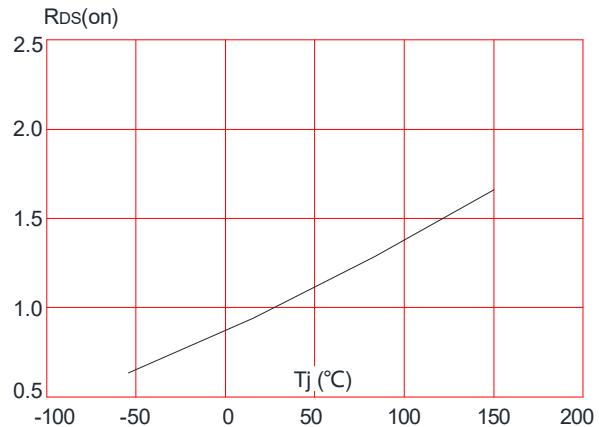
**Figure 6:** Capacitance Characteristics



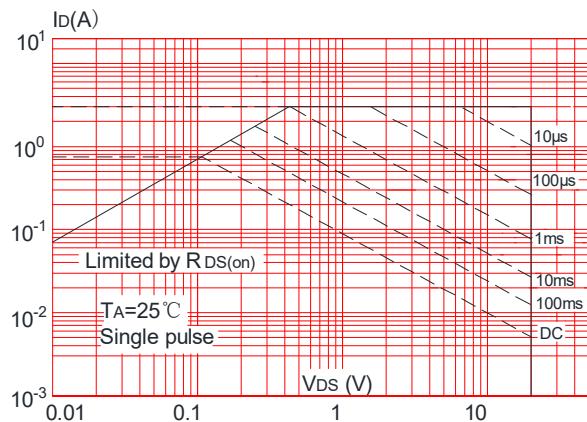
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



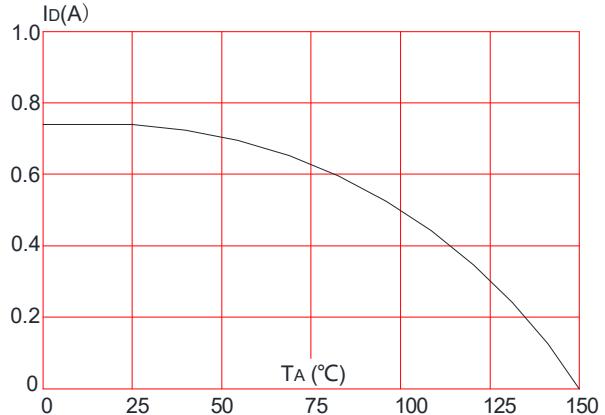
**Figure 8:** Normalized on Resistance vs. Junction Temperature



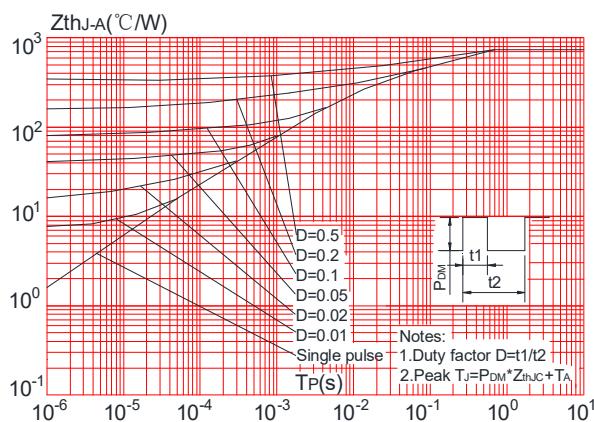
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



## Test Circuit

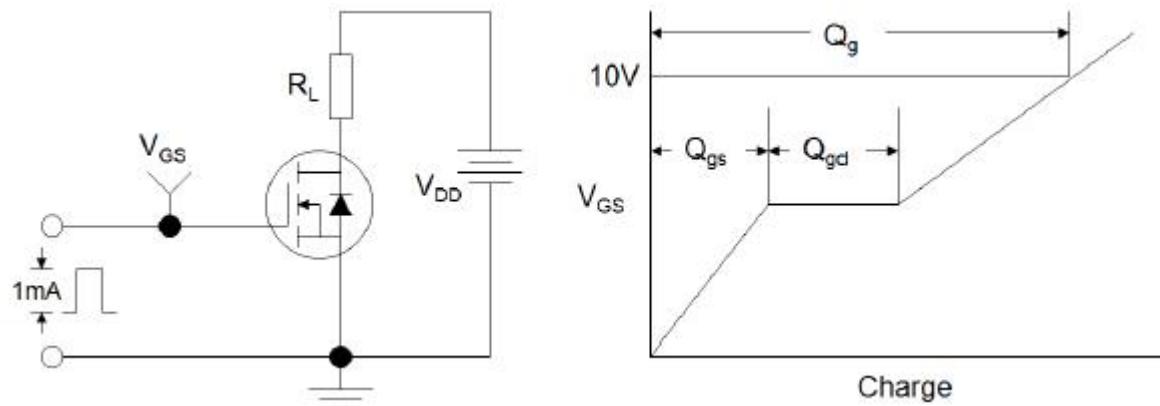


Figure 1: Gate Charge Test Circuit & Waveform

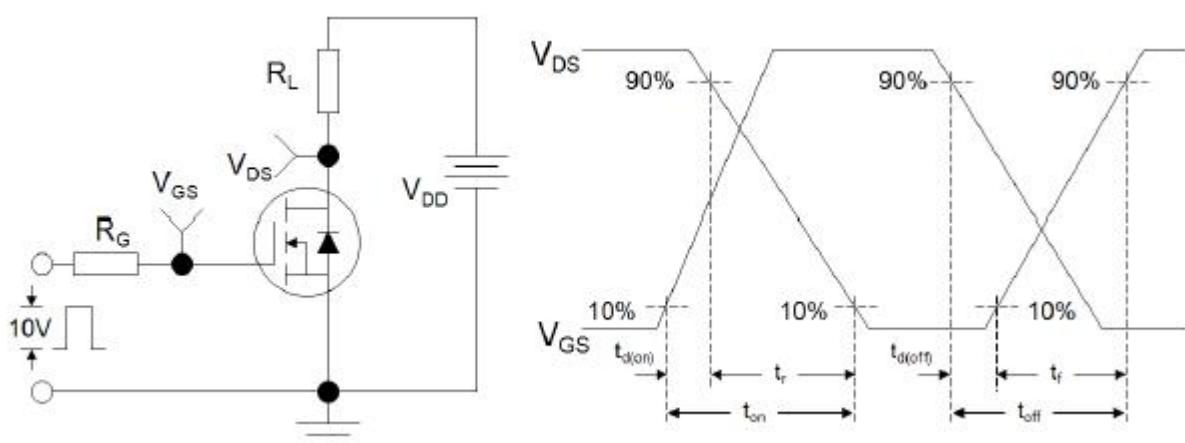


Figure 2: Resistive Switching Test Circuit & Waveforms

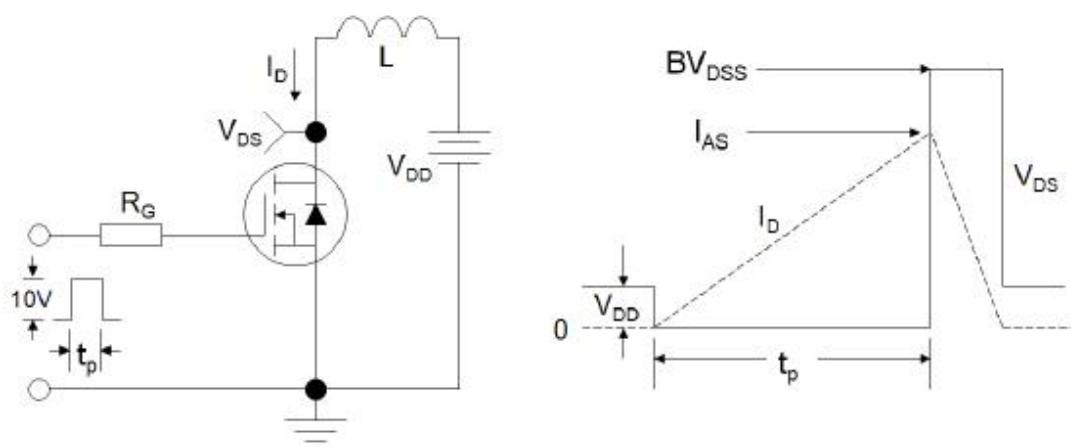
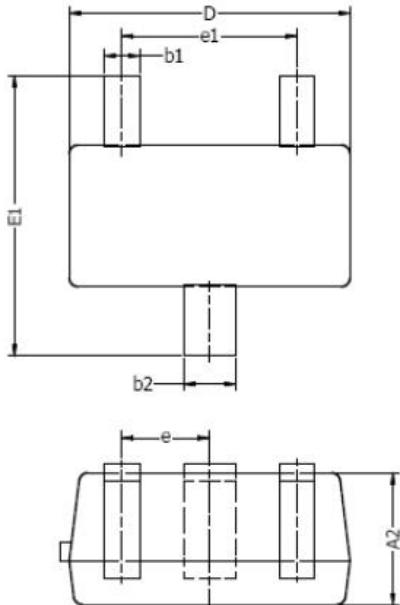


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms



## Package Mechanical Data-SOT-523-3L



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
A1	0.00	0.10	0.000	0.004
A2	0.70	0.80	0.028	0.031
b1	0.15	0.25	0.006	0.010
b2	0.25	0.35	0.010	0.014
c	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
E1	1.45	1.75	0.057	0.069
e	0.50 TYP.		0.020 TYP.	
e1	0.90	1.10	0.035	0.043
L	0.40 REF.		0.016 REF.	
L1	0.10	0.30	0.004	0.012
$\theta$	0°	8°	0°	8°

## NOTES:

1. Above package outline conforms to JEITA EAIJ ED-7500A SC-75A.
2. Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

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